DATA SHEET

BFG67; BFG67/X; BFG67R; BFG67/XR
NPN 8 GHz wideband transistor

Product specification
File under Discrete Semiconductors, SC14

September 1995

Philips Semiconductors

PHILIPS

FEATURES

- High power gain
- Low noise figure
- High transition frequency
- Gold metallization ensures excellent reliability.

DESCRIPTION

The BFG67 is a silicon npn transistor in a 4-pin, dual-emitter plastic SOT143 envelope. It is available as in-line emitter pinning (BFG67) and cross emitter pinning (BFG67/X). Versions with reverse pinning (BFG67R and BFG67/XR) are available upon request.

This transistor is designed for wideband applications in the GHz range, such as satellite TV tuners and portable RF communications equipment.

PINNING

PIN	DESCRIPTION
BFG67 (Fig.1) Code: V3.	
1	collector
2	base
3	emitter
4	emitter
BFG67/X (Fig.1) Code: V12	
1	collector
2	emitter
3	base
4	emitter
BFG67R (Fig.2) Code: V27	
1	collector
2	base
3	emitter
4	emitter
BFG67/XR (Fig.2) Code: V26	
1	collector
2	emitter
3	base
4	emitter

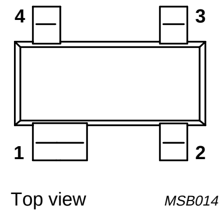


Fig.1 SOT143.

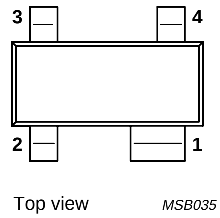


Fig.2 SOT143R.

QUICK REFERENCE DATA

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
V_{CEO}	collector-emitter voltage	open base	–	–	10	V
I_C	DC collector current		–	–	50	mA
P_{tot}	total power dissipation	up to T_s = 65 °C (note 1)	–	–	300	mW
C_{re}	feedback capacitance	$I_C = i_c = 0$; V_{CB} = 8 V; f = 1 MHz	–	0.5	–	pF
f_T	transition frequency	I_C = 15 mA; V_{CE} = 8 V; f = 500 MHz	–	8	–	GHz
G_{UM}	maximum unilateral power gain	I_C = 15 mA; V_{CE} = 8 V; T_{amb} = 25 °C; f = 1 GHz	–	17	–	dB
F	noise figure	$\Gamma_s = \Gamma_{opt}$; I_C = 5 mA; V_{CE} = 8 V; T_{amb} = 25 °C; f = 1 GHz	–	1.3	–	dB
		$\Gamma_s = \Gamma_{opt}$; I_C = 5 mA; V_{CE} = 8 V; T_{amb} = 25 °C; f = 2 GHz	–	2.2	–	dB

Note

1. T_s is the temperature at the soldering point of the collector tab.

LIMITING VALUES

In accordance with the Absolute Maximum System (IEC 134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V_{CBO}	collector-base voltage	open emitter	–	20	V
V_{CEO}	collector-emitter voltage	open base	–	10	V
V_{EBO}	emitter-base voltage	open collector	–	2.5	V
I_C	DC collector current		–	50	mA
P_{tot}	total power dissipation	up to T_s = 65 °C (note 1)	–	380	mW
T_{stg}	storage temperature range		–65	150	°C
T_j	junction temperature		–	175	°C

THERMAL RESISTANCE

SYMBOL	PARAMETER	THERMAL RESISTANCE
$R_{th\ j\text{-}s}$	from junction to soldering point (note 1)	290 K/W

Note

1. T_s is the temperature at the soldering point of the collector tab.

CHARACTERISTICS

T_j = 25 °C unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
I_{CBO}	collector cut-off current	open emitter; I_E = 0; V_{CB} = 5 V	–	–	50	nA
h_{FE}	DC current gain	I_C = 15 mA; V_{CE} = 5 V	60	100	–	
f_T	transition frequency	I_C = 15 mA; V_{CE} = 8 V; f = 500 MHz	–	8	–	GHz
C_c	collector capacitance	$I_E = i_e$ = 0; V_{CB} = 8 V; f = 1 MHz	–	0.7	–	pF
C_e	emitter capacitance	$I_C = i_c$ = 0; V_{EB} = 0.5 V; f = 1 MHz	–	1.3	–	pF
C_{re}	feedback capacitance	$I_C = i_c$ = 0; V_{CB} = 8 V; f = 1 MHz	–	0.5	–	pF
G_{UM}	maximum unilateral power gain (note 1)	I_C = 15 mA; V_{CE} = 8 V; T_{amb} = 25 °C; f = 1 GHz	–	17	–	dB
		I_C = 15 mA; V_{CE} = 8 V; T_{amb} = 25 °C; f = 2 GHz	–	10	–	dB
F	noise figure	$\Gamma_s = \Gamma_{opt}$; I_C = 5 mA; V_{CE} = 8 V; T_{amb} = 25 °C; f = 1 GHz	–	1.3	–	dB
		$\Gamma_s = \Gamma_{opt}$; I_C = 15 mA; V_{CE} = 8 V; T_{amb} = 25 °C; f = 1 GHz	–	1.7	–	dB
		I_C = 5 mA; V_{CE} = 8 V; T_{amb} = 25 °C; f = 2 GHz; Z_S = 60 Ω	–	2.5	–	dB
		I_C = 15 mA; V_{CE} = 8 V; T_{amb} = 25 °C; f = 2 GHz; Z_S = 60 Ω	–	3	–	dB

Note

1. G_{UM} is the maximum unilateral power gain, assuming S_{12} is zero and $G_{UM} = 10\ \log \frac{|s_{21}|^2}{(1-|s_{11}|^2)\ (1-|s_{22}|^2)}$ dB.

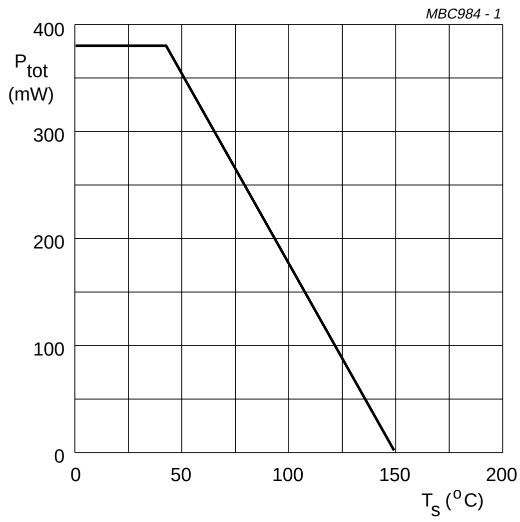
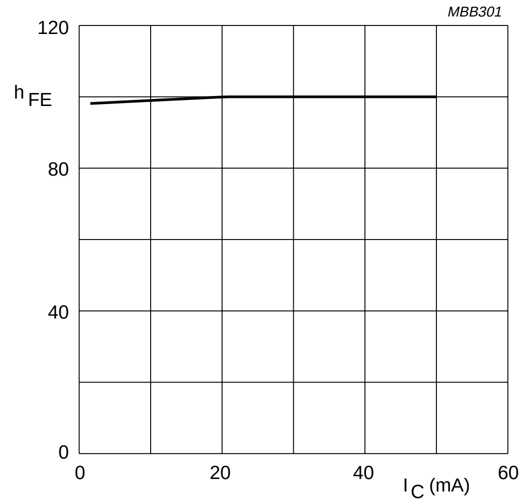
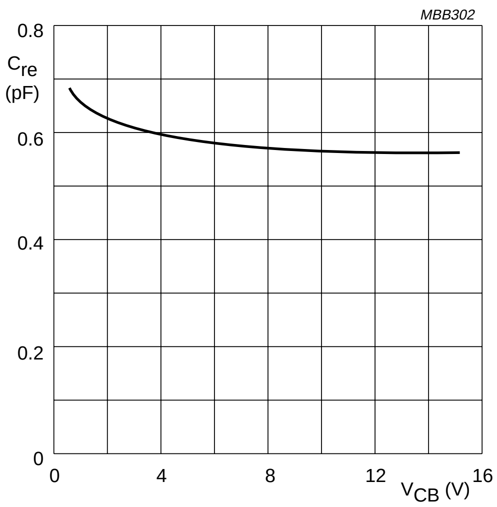


Fig.3 Power derating curve.



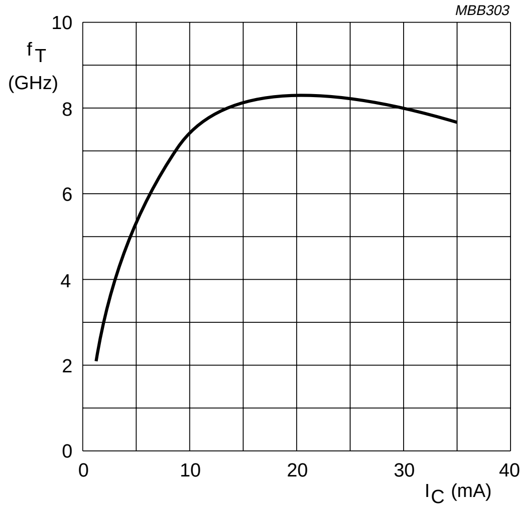
V_{CE} = 5 V.

Fig.4 DC current gain as a function of collector current.



$I_C = i_c = 0$; f = 1 MHz.

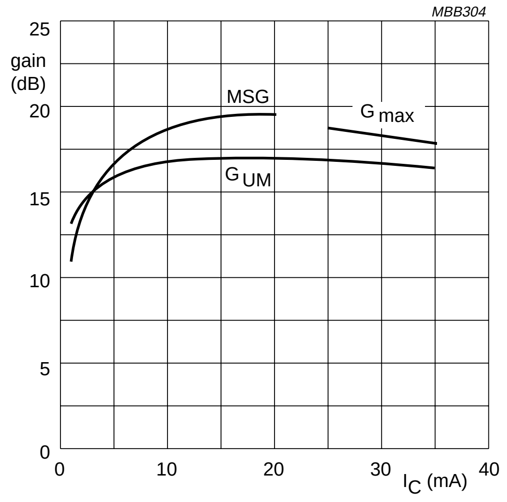
Fig.5 Feedback capacitance as a function of collector-base voltage.



V_{CE} = 8 V; T_{amb} = 25 °C; f = 2 GHz.

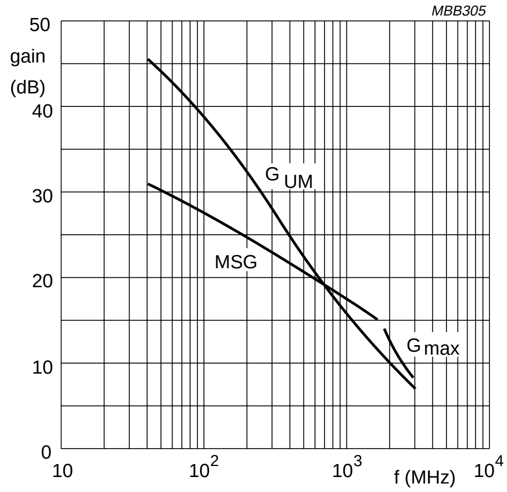
Fig.6 Transition frequency as a function of collector current.

In Figs 7 to 10, G_{UM} = maximum unilateral power gain; MSG = maximum stable gain; G_{max} = maximum available gain.



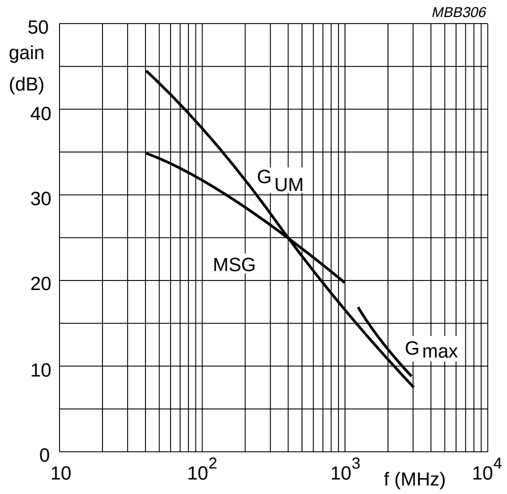
V_{CE} = 8 V; f = 1 GHz.

Fig.7 Gain as a function of collector current.



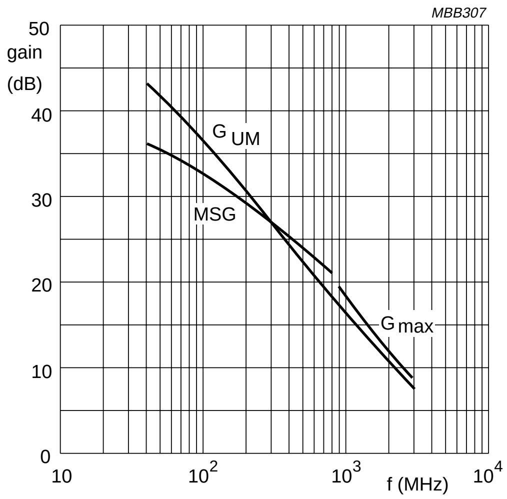
V_{CE} = 8 V; I_C = 5 mA.

Fig.8 Gain as a function of frequency.



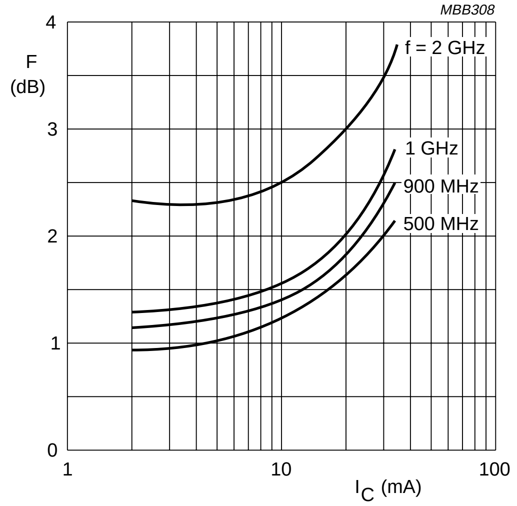
V_{CE} = 8 V; I_C = 15 mA.

Fig.9 Gain as a function of frequency.



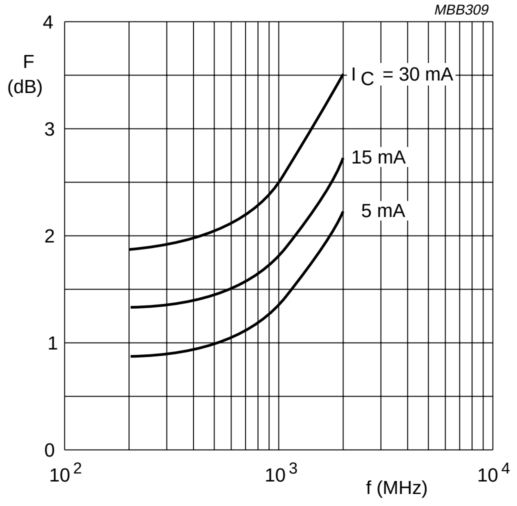
V_{CE} = 8 V; I_C = 30 mA.

Fig.10 Gain as a function of frequency.



V_{CE} = 8 V.

Fig.11 Minimum noise figure as a function of collector current.



V_{CE} = 8 V.

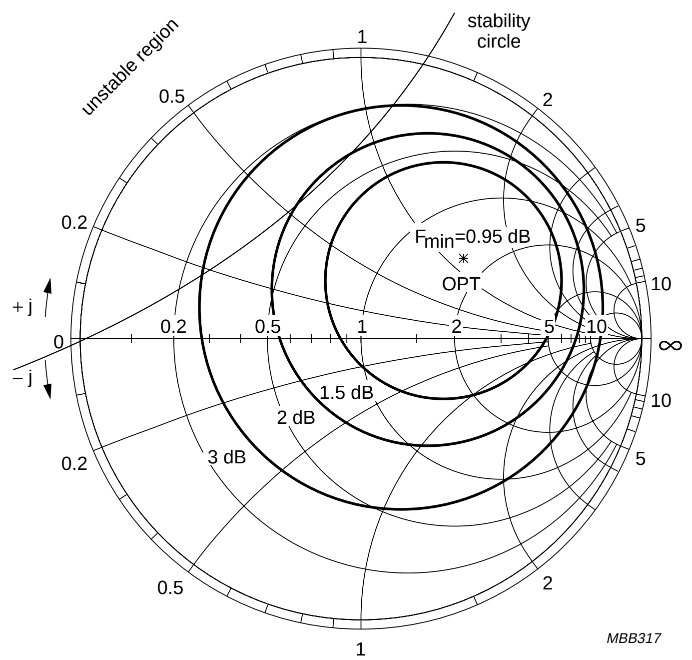
Fig.12 Minimum noise figure as a function of frequency.

BFG67/X

f (MHz)	V_{CE} (V)	I_C (mA)
500	8	5

Noise Parameters

F_{min} (dB)	Gamma (opt)		$R_n/50$
	(mag)	(ang)	
0.95	0.455	33.8	0.288



Z_O = 50 Ω.

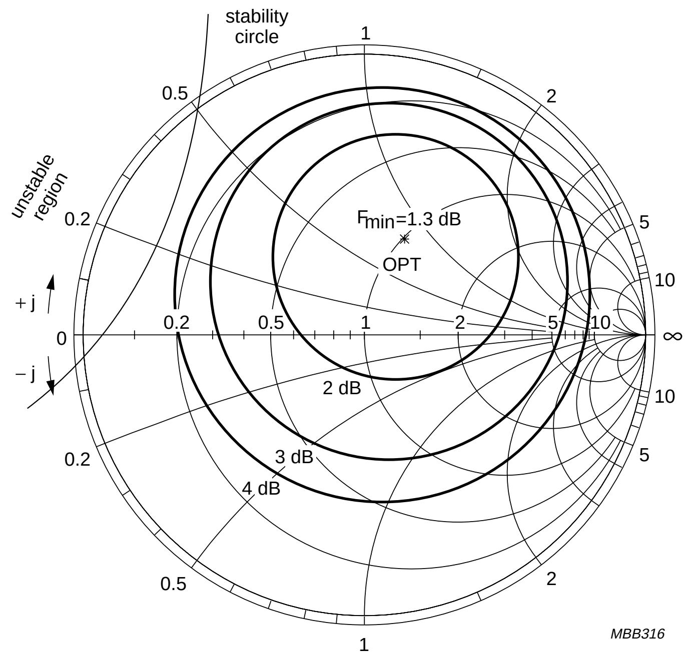
Fig.13 Noise circle figure.

BFG67/X

f (MHz)	V_{CE} (V)	I_C (mA)
1000	8	5

Noise Parameters

F_{min} (dB)	Gamma (opt)		$R_n/50$
	(mag)	(ang)	
1.3	0.375	65.9	0.304



Z_O = 50 Ω.

Fig.14 Noise circle figure.

BFG67/X

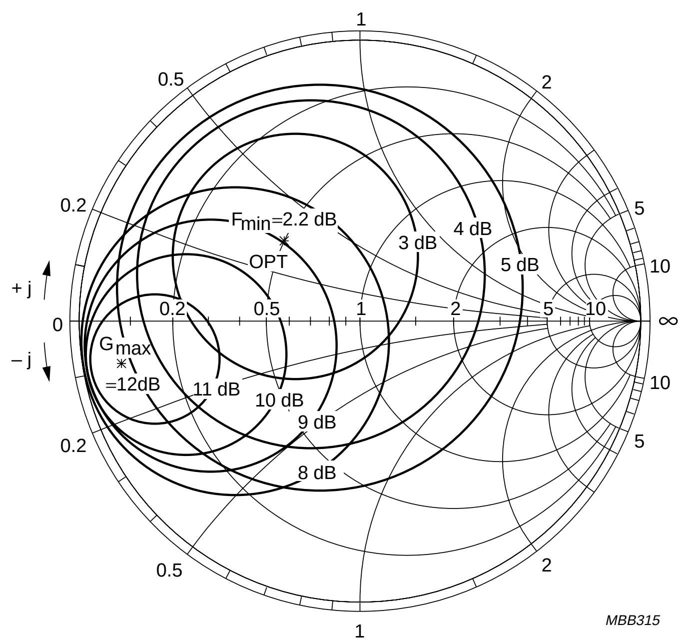
f (MHz)	V_{CE} (V)	I_C (mA)
2000	8	5

Noise Parameters

F_{min} (dB)	Gamma (opt)		$R_n/50$
	(mag)	(ang)	
2.2	0.391	136.5	0.184

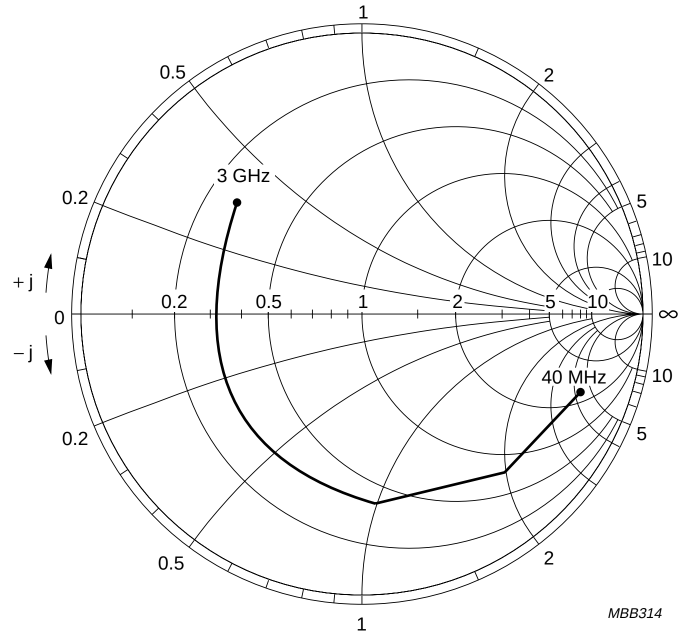
Average Gain Parameters

G_{MAX} (dB)	Gamma (max)	
	(mag)	(ang)
12	0.839	–170



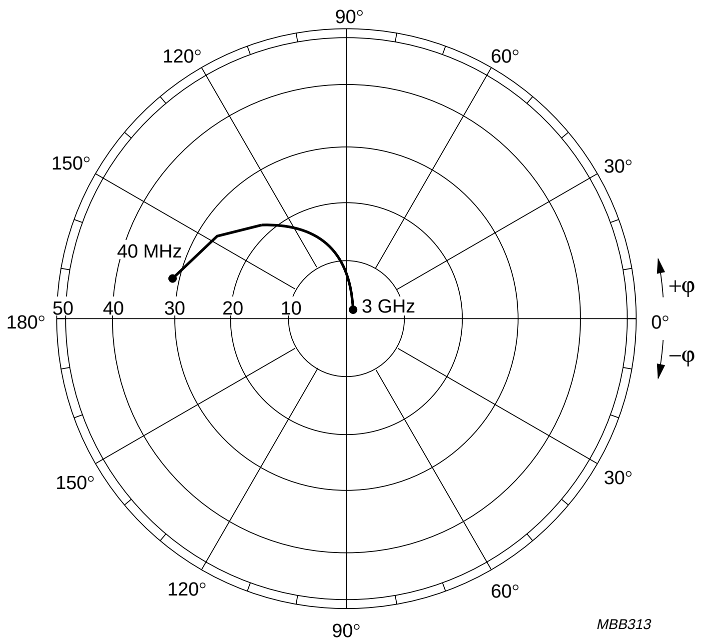
Z_O = 50 Ω.

Fig.15 Noise circle figure.



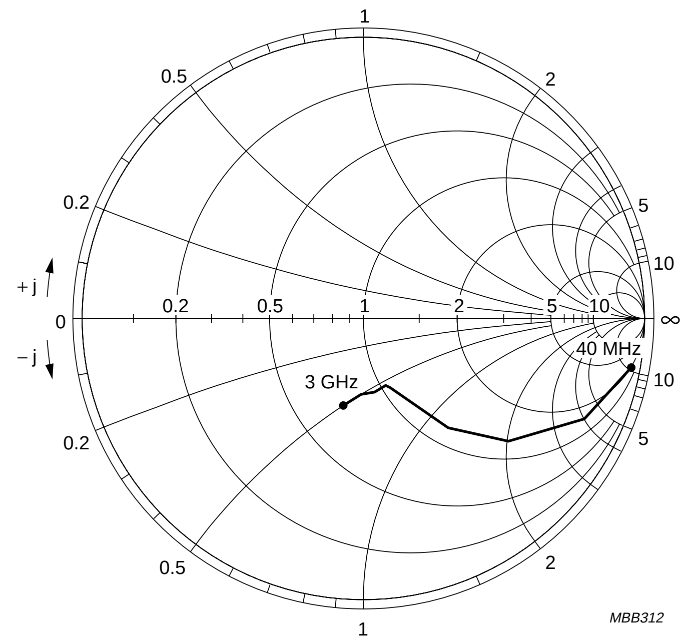
V_{CE} = 8 V; I_C = 15 mA; Z_O = 50 Ω.

Fig.16 Common emitter input reflection coefficient (S_{11}).



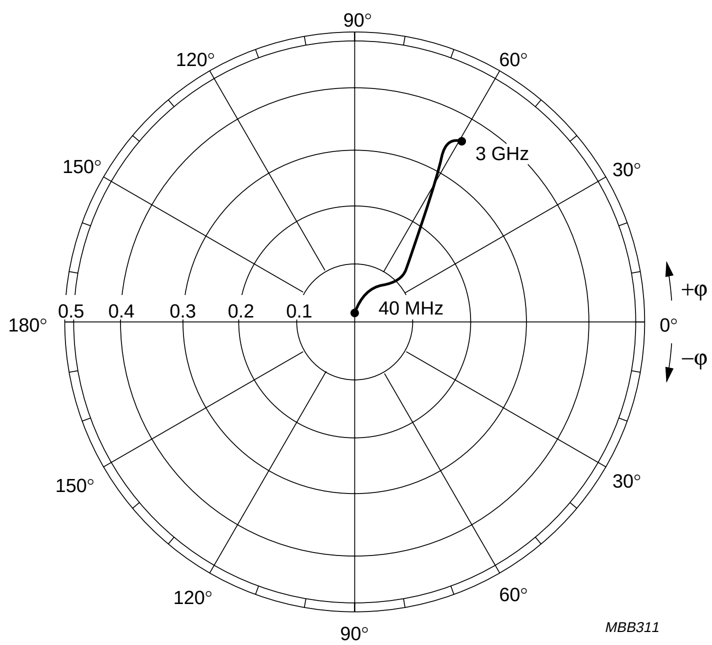
V_{CE} = 8 V; I_C = 15 mA; Z_O = 50 Ω.

Fig.17 Common emitter forward transmission coefficient (S_{21}).



V_{CE} = 8 V; I_C = 15 mA.

Fig.18 Common emitter reverse transmission coefficient (S_{12}).

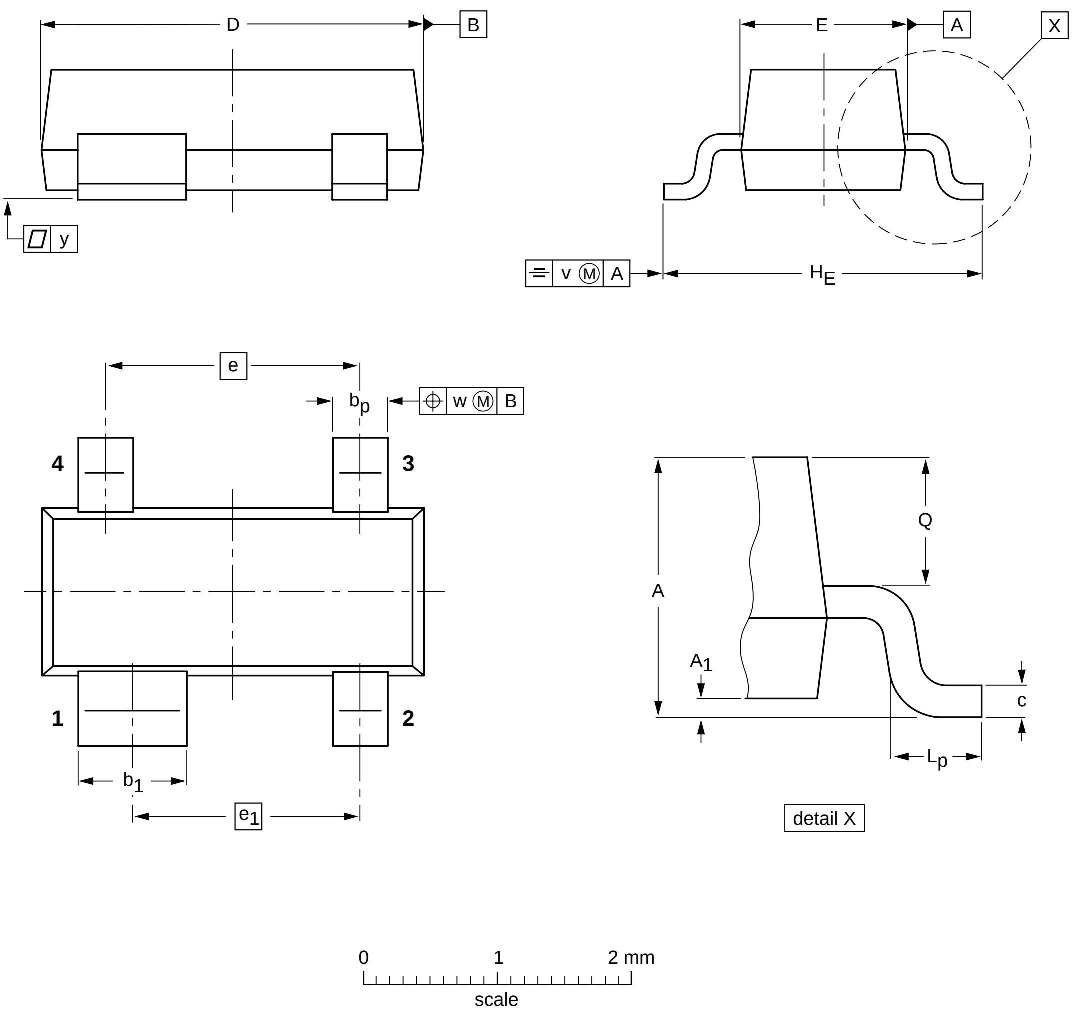


V_{CE} = 8 V; I_C = 15 mA.

Fig.19 Common emitter output reflection coefficient (S_{22}).

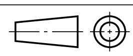
PACKAGE OUTLINES

Plastic surface mounted package; 4 leads **SOT143B**

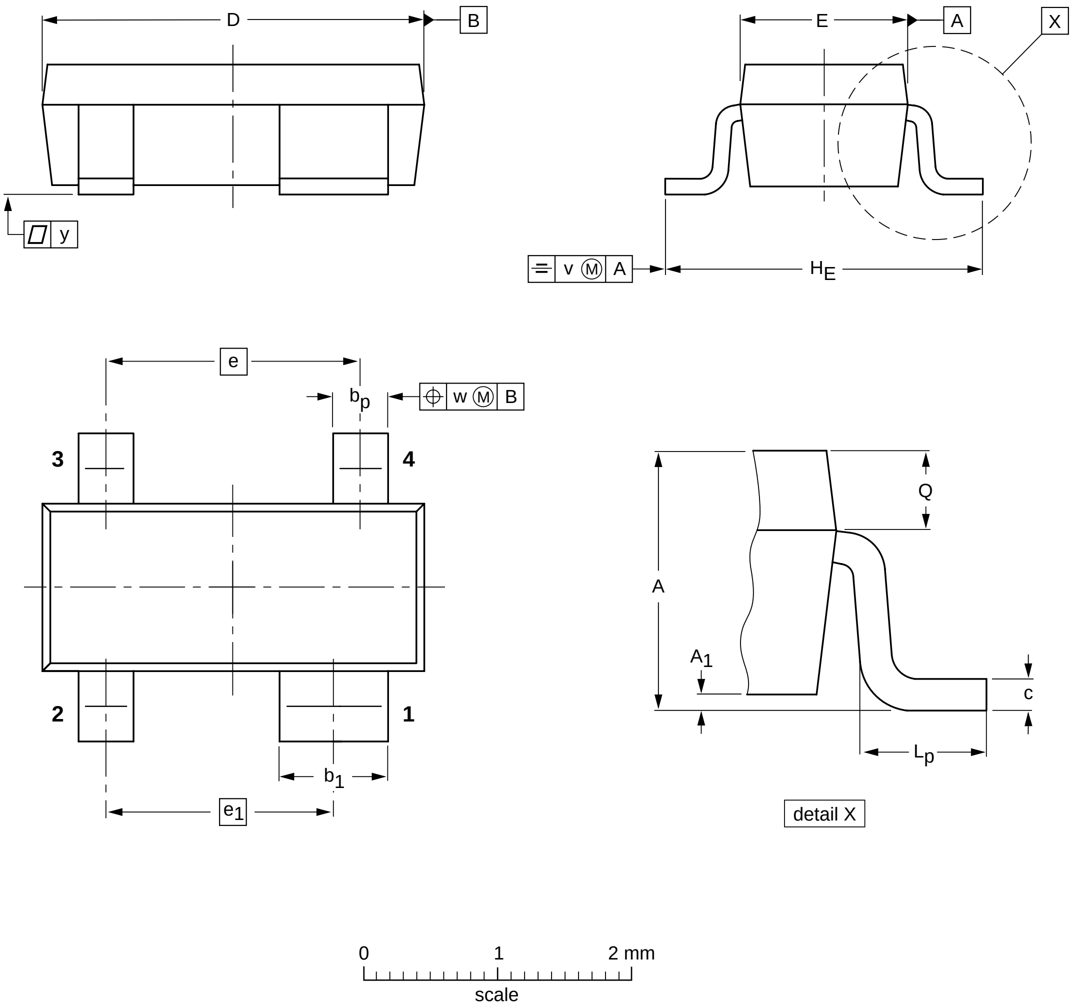


DIMENSIONS (mm are the original dimensions)

UNIT	A	A_1 max	b_p	b_1	c	D	E	e	e_1	H_E	L_p	Q	v	w	y
mm	1.1 0.9	0.1	0.48 0.38	0.88 0.78	0.15 0.09	3.0 2.8	1.4 1.2	1.9	1.7	2.5 2.1	0.45 0.15	0.55 0.45	0.2	0.1	0.1

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ			
SOT143B						97-02-28

Plastic surface mounted package; reverse pinning; 4 leads **SOT143R**



DIMENSIONS (mm are the original dimensions)

UNIT	A	A_1 max	b_p	b_1	c	D	E	e	e_1	H_E	L_p	Q	v	w	y
mm	1.1 0.9	0.1	0.48 0.38	0.88 0.78	0.15 0.09	3.0 2.8	1.4 1.2	1.9	1.7	2.5 2.1	0.55 0.25	0.45 0.25	0.2	0.1	0.1

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ			
SOT143R						97-03-10

DEFINITIONS

Data Sheet Status	
Objective specification	This data sheet contains target or goal specifications for product development.
Preliminary specification	This data sheet contains preliminary data; supplementary data may be published later.
Product specification	This data sheet contains final product specifications.

Limiting values

Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.

Application information

Where application information is given, it is advisory and does not form part of the specification.

LIFE SUPPORT APPLICATIONS

These products are not designed for use in life support appliances, devices, or systems where malfunction of these products can reasonably be expected to result in personal injury. Philips customers using or selling these products for use in such applications do so at their own risk and agree to fully indemnify Philips for any damages resulting from such improper use or sale.